

TOD-F2281AME-B-1-HF

Dual Digit Display LED

Part Number	Chip		Face Color	Segment Color
	Material	Source Color		
TOD-F2281AME-B-1-HF	AlGaInP	Ultra-orange	Black	White

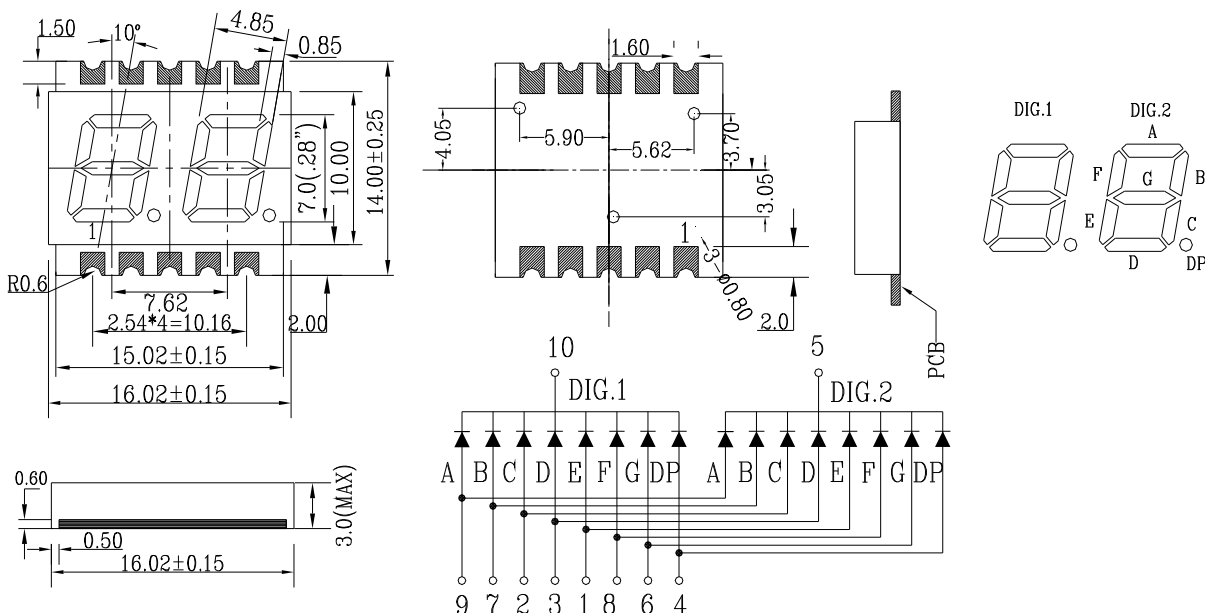
Features

- (0.28") 7.0mm digit height
- Common Cathode
- I.C. compatible
- Low power consumption
- RoHS compliant
- Moisture sensitivity level:2a

Applications

- Audio equipment
- Instrument panels
- Digital read out display

Package Dimensions & Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters, tolerance: ± 0.25 ; Angle: $\pm 0.1^\circ$ unless otherwise noted.
2. Specifications are subject to change without notice.

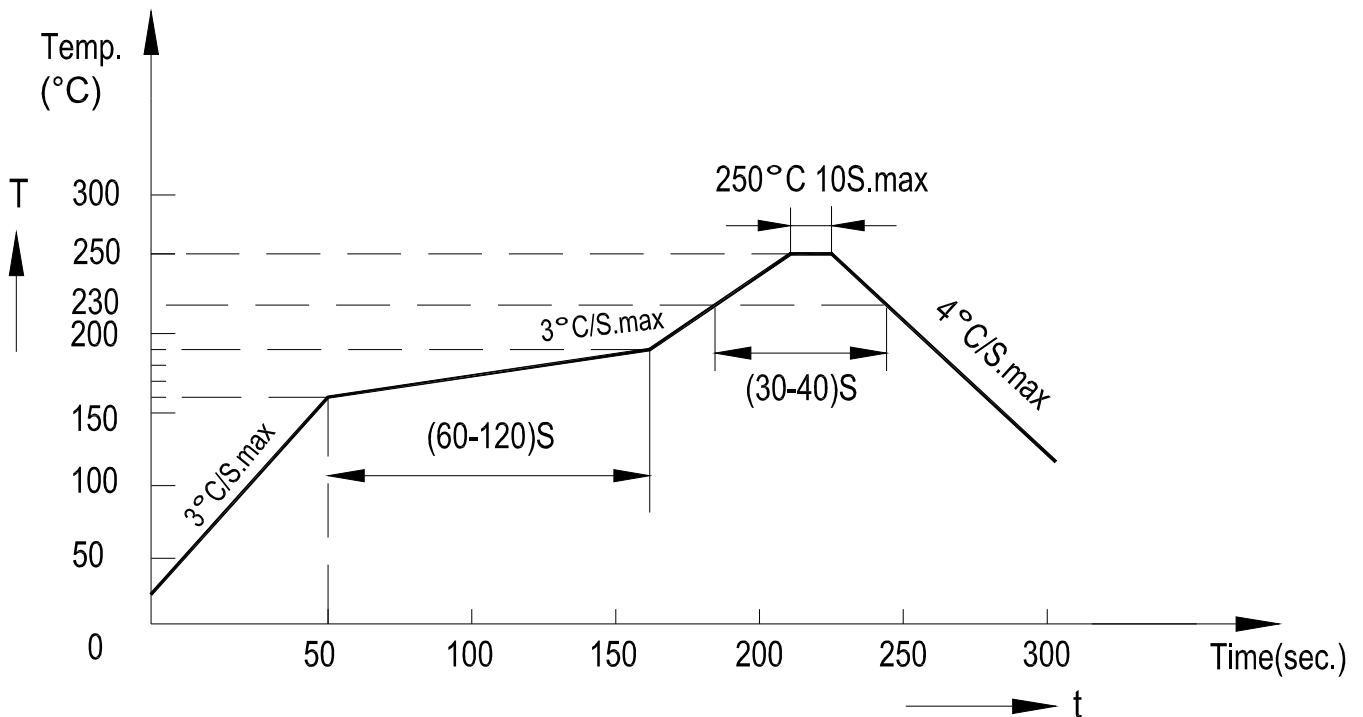
Absolute Maximum Rating @ Ta=25°C

Parameter	Maximum Rating	Unit
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width) Per Dice	80	mA
Power Dissipation Per Dice	75	mW
Continuous Forward Current Per Dice	20	mA
Recommend Operating Current Per Dice	12	mA
Reverse Voltage Per Dice	5	V
Operating Temperature Range	-25°C to +85°C	
Storage Temperature Range	-30°C to +85°C	
Manual soldering temperature	Max 320°C for 3 Sec	

Electrical / Optical Characteristic @ Ta=25°C

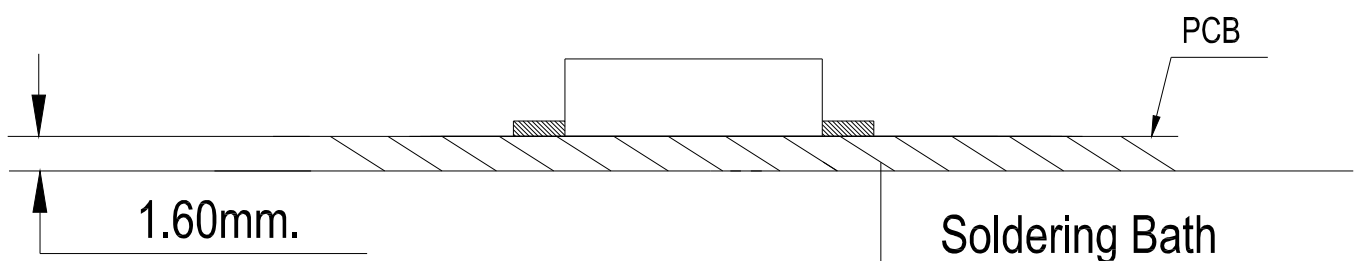
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition	Grade
Dominant Wavelength	λ_d		623		nm	$I_F=20\text{mA}$	
Spectral Line Half-Width	$\Delta\lambda$		17		nm	$I_F=20\text{mA}$	
Forward Voltage Per Dice	V_F	1.8	2.0	2.3	V	$I_F=20\text{mA}$	
Reverse Current Per Dice	I_R			100	μA	$V_R=5\text{V}$	
Luminous Intensity Matching Rate	Iv-m			2.0:1		$I_F=20\text{mA}$	

Soldering Profile

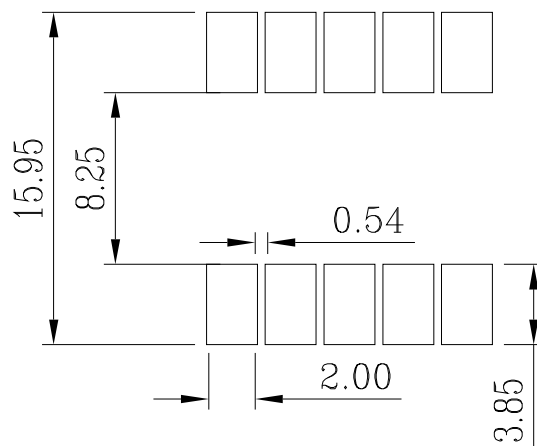


Number of reflow process shall be 2 times or less

1. Manual soldering temperature : Max 320°C for 3 Sec e the soldered area is to be smoothly covered with soldering, can delay the soldering time, but not to exceed
2. Can be second manual soldering, but must be cooling before second manual soldering, In order to guaranteed 20s every pad, because if that, the pad will be damaged.
3. The minimum distance of display seating plan to soldering bath is 1.6mm.
4. Don't cause stress to the epoxy resin while it is exposed to high temperature.



Recommended Soldering Pattern and Storage Condition



1. This part is a moisture sensitive device, According to JEDEC level 4.
2. The storage condition of packed: $\leq 40^{\circ}$ / 90%RH, 12 months or $\leq 10\%$ RH
3. The storage condition of unpacked: $\leq 30^{\circ}$ / 60%RH, 72 Hrs or $\leq 10\%$ RH

This part can endure ultrasonic cleaning, the solvent hydrocarbon is suitable but isopropyl-alcohol base is not.